

▶ PCB LEAD TIMES

STANDARD LEAD TIME - 20 Working Day

Technology	1 Day	2 Day	3 Day	5 Day	7 Day	10 Day
1 - 4 Layers	X	X	X	X	X	X
6 - 10 Layers		X	X	X	X	X
> 10 Layers			X	X	X	X

** Prototype and Production Quantities Available*

▶ STANDARD PCB FEATURES

- Solder Mask.....Green, Blue, Red, Black, Clear
- Min Solder Mask Web..... .004"
- Max Board Thickness..... .250"
- Maximum Board Size..... 22" x 42"
- Max Copper Weight..... 6 oz
- Standard SMD Pitch..... .016"

▶ PRINTED CIRCUIT BOARD CAPABILITIES

Surface Finishes

- ENIG
- HASL
- Pb Free HASL
- Immersion Silver & Tin
- ENEPIG
- Hard Body Gold
- Soft Bondable Gold
- OSP

Materials

- FR-4 – ALL Types
- CEM-1 & CEM-3
- Heavy Copper
- RF and High Speed Materials
- Mixed Materials / FR-4 Teflon
- Metal Backed Boards
- Polyimide

Drill & Rout

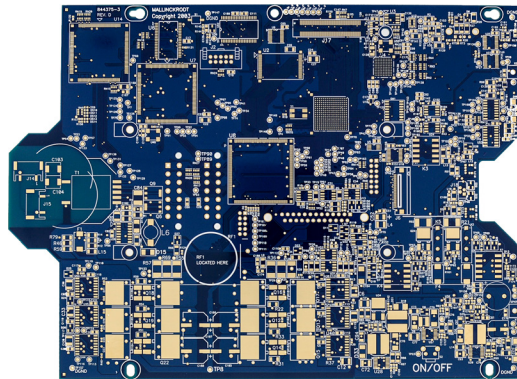
- Jump Score
- Counter Sinks / Counter Bores
- Control Depth & Laser Drilling
- 12:1 Aspect Ratio
- Depth Controlled Milling

Design

- 1 to 18 Layers
- 3 Mil Lines & Spaces
- IPC Class 2 / Class 3
- Impedance Control +/-10%
- Down to .006" Holes
- Blind & Buried Vias
- Silver Thru Hole
- Via in Pad
- Laser Direct Imaging
- MicroVia's

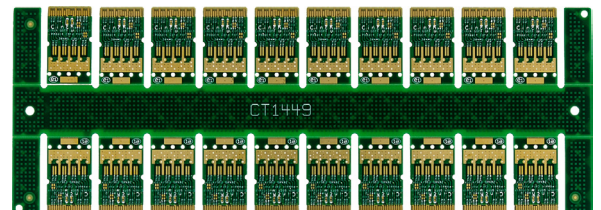
Plating

- Conductive Via Fill
- Edge Plating
- Castellations
- Plated Slots
- Gold Tabs
- Plasma Etch Back
- Peelable Solder Mask



▶ ADVANCED PCB TECHNOLOGY

- Design Services
- Flex & Rigid Flex
- ITAR Registered
- Thermal Management
- High Density Interconnects
- MIL-PRF-55110
- Sequential Lamination
- Net List Compare
- Ionic Cleanliness
- Free DFx File Check



▶ TECHNOLOGY ROAD MAP

	Standard	Advanced
Mechanical		
Maximum Layer Count	18	26
Maximum Board Thickness	.250"	.287"
Maximum Board Size	20" x 23"	20" x 24"
Smallest Hole Size (Finished)	.006"	.005"
Aspect Ratio	11:01	12:01
Minimum Component Pitch	.020" (soldermask between pins)	.016" (gang masked)
Minimum Core Thickness	.003"	.002"
Jump Scoring	Yes	Yes
Countersinks/Counterbores	Yes	Yes
Plated Hole Tolerance	+/- .003"	+/- .002"
Warpage	1%	0.75%
Copper Weight		
Inner Layers	4 ounces	4 ounces
Outer Layers	6 ounces	8 ounces
Technology		
Impedance Control	+/- 10%	+/- 5%
Via Technology	Blind/Buried	Blind/Buried
Laser Drilling (Microvias)	Yes	Yes
Plasma Etching	Yes	Yes
Laser Direct Imaging	Yes	Yes
Via Filling	Non-Conductive	Conductive
Available Surface Finishes		
	HASL	Immersion Silver
	ENIG	OSP
	Pb Free HASL	Immersion Gold
	Immersion Tin	Electroplated Gold
Materials		
	FR-4 (140-220 Tg)	Teflon
	Polyimide	Thermagon
	CEM-1	Arlon
	Rogers	Getek
Agency Qualifications		
UL (File #E86319) ISO-9001:2008 TS-16949 IPC-6012 Class 3		

Standard - Everyday Capability

Advanced - Everyday Capability with a small premium.

Epec's diverse and growing base of more than 2500 customers represents a wide range of markets including electronics, medical, industrial, communications, access controls, automotive, computing, military, and includes leading OEM's, contract manufacturers, and electronics manufacturing services (EMS) providers.

Contact us today, to experience why Epec has become one of the fastest growing Engineered Electronic Product providers in North America!

Toll-Free: 888-995-5171

Main: 508-995-5171

www.epectec.com